

3.2x2.4mm SMD CHIP LED LAMP

Part Number: APBD3224SURKCGKC-F01

Hyper Red Green

Features

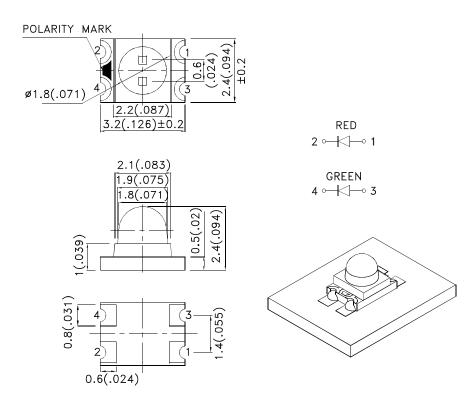
- 3.2x2.4mm SMT LED, 2.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with AlGalnP on GaAs substrate Light Emitting Diode.

Package Dimensions



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APPROVED: WYNEC

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
APBD3224SURKCGKC-F01	Hyper Red (AlGaInP)	Water Clear	700	1300	20°
	Green (AlGaInP)	Water Clear	120	300	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	650 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I==20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	I==20mA
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I==20mA
lR	Reverse Current	Hyper Red Green		10 10	uA	V _R = 5V

Notes:

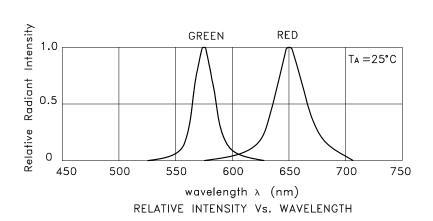
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

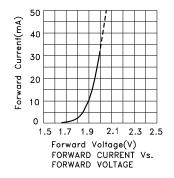
Parameter	Hyper Red	Green	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage	5				
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

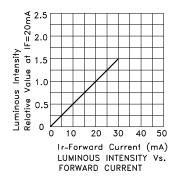
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

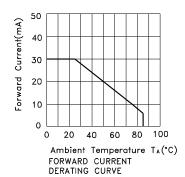
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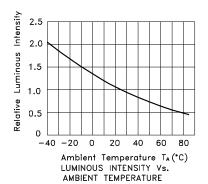


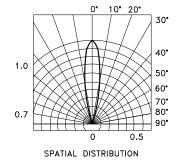
APBD3224SURKCGKC-F01 Hyper Red







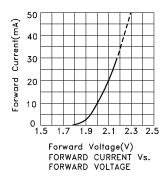


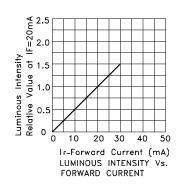


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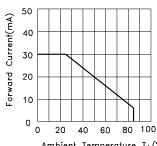
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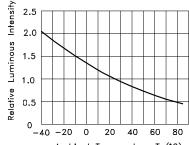
Green

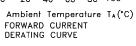




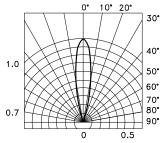
2.5











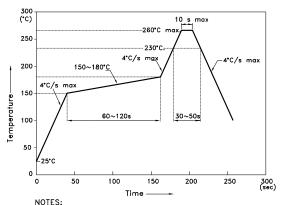
SPATIAL DISTRIBUTION

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



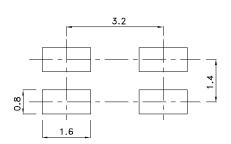
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

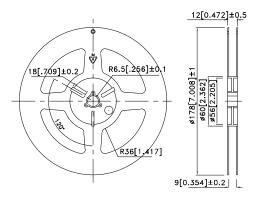
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - to high temperature.

 3.Number of reflow process shall be 2 times or less.

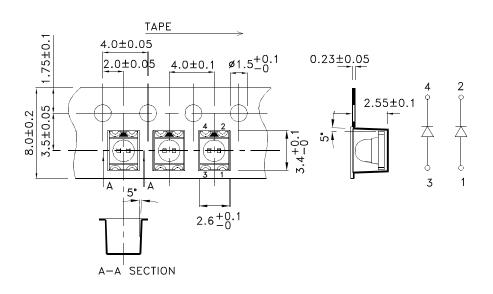
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)

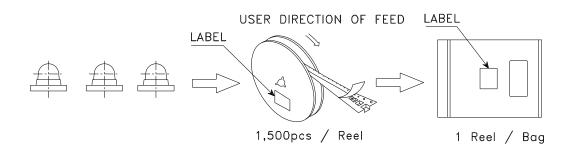


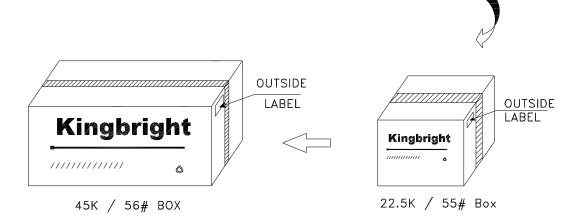
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PACKING & LABEL SPECIFICATIONS

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